

Amendments to the Claims:

This Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-130. (Cancelled)

131. (Original) A method for making a silver-containing film, the method comprising the steps of:

applying a layer of paste to a substrate, said paste including particles dispersed in a carrier liquid, said particles including a metallic phase with greater than about 30 weight percent silver;

removing said carrier liquid from said layer of paste and forming on said substrate a densified layer including silver from said particles;

wherein, said particles being substantially spheroidal, having a weight average size of from about 0.1 micron to about 4 microns, having a size distribution such that at least about 90 weight percent of said particles are smaller than about twice said weight average size and having a mean crystallite size of larger than about 50 nanometers.

132. (Original) The process of Claim 131, wherein:

said particles are comprised substantially of only said metallic phase.

133. (Original) The method of Claim 131, wherein:

said metallic phase comprises a first material phase and said particles further comprise a second material phase being substantially free of silver.

134. (Original) The method of Claim 133, wherein:

said first material phase comprises greater than about 50 weight percent of said particles.

135. (Original) The method of Claim 133, wherein:

said second material phase comprises less than about 30 weight percent of said particles.

136. (Original) The method of Claim 133, wherein:

said first material phase is electrically conductive and said second material phase is dielectric.

137. (Original) The method of Claim 133, wherein:
said substrate comprises a dielectric material for a capacitor and said second material phase of said particles also comprises said dielectric material.
138. (Original) The method of Claim 137, wherein:
said dielectric material is a titanate.
139. (Original) The method of Claim 133, wherein:
said second material phase comprises an oxide material.
140. (Original) The method of Claim 133, wherein:
said second material phase comprises a ceramic material.
141. (Original) The method of Claim 131, wherein:
said step of forming on said substrate a film including silver from said particles comprises heating said particles, on said substrate, to a temperature of greater than about 300°C.
142. (Original) The method of Claim 131, wherein:
said method further comprises preparing a structure of stacked layers including a plurality of first layers including a dielectric material and second layers including said particles; and
heating said structure to a temperature of greater than about 300°C to form a microelectronic structure including a plurality of silver-containing films, having silver from said particles, and including a plurality of dielectric layers, with at least one of said dielectric layers being between two adjacent of said silver-containing films.
143. (Currently Amended) The method of Claim 131, wherein:
said particles including silver are first particles and ~~the particulate product said paste further comprises~~ comprises second particles, compositionally different from said first particles, and including palladium.
144. (New) The method of Claim 133, wherein said second material phase is a coating substantially covering the first material phase.
145. (New) The method of Claim 131, wherein said silver-containing film is a electromagnetic shielding film.
146. (New) The method of Claim 131, wherein said silver-containing film is a silver metallized termination.
147. (New) The method of Claim 131, wherein said silver-containing film is a

thermally conductive film.

148. (New) The method of Claim 131, wherein said silver-containing film is a light reflecting surface.

149. (New) An electronic component incorporating the silver-containing film made by the method of Claim 131.

150. (New) A capacitor incorporating the silver-containing film made by the method of Claim 131.

151. (New) An inductor incorporating the silver-containing film made by the method of Claim 131.

152. (New) A resistor incorporating the silver-containing film made by the method of Claim 131.

153. (New) A fuse incorporating the silver-containing film made by the method of Claim 131.

154. (New) A multi-chip module incorporating the silver containing film made by the method of Claim 131.

155. (New) A serpentine resistor circuit incorporating the silver-containing film made by the method of Claim 131.

156. (New) A cellular phone incorporating the silver-containing film made by the method of Claim 131.

157. (New) A computer incorporating the silver-containing film made by the method of Claim 131.

158. (New) A resonator incorporating the silver metallized termination made by the method of Claim 131.

159. (New) A trimmer incorporating the silver-containing film made by the method of Claim 131.

160. (New) A potentiometer incorporating the silver-containing film made by the method of Claim 131.

161. (New) A thermister incorporating the silver-containing film made by the method of Claim 131.

162. (New) A varistor incorporating the silver-containing film made by the method of Claim 131.

163. (New) A wrap-around termination for a hybrid circuit incorporating the silver-

containing film made by the method of Claim 131.

164. (New) A liquid crystal display panel incorporating the silver-containing film made by the method of Claim 131.

165. (New) A window defogger/deicer incorporating the silver-containing film made by the method of Claim 131.

166. (New) A photovoltaic grid electrode incorporating the silver-containing film made by the method of Claim 131.

167. (New) A plasma flat panel display electrode incorporating the silver-containing film made by the method of Claim 131.

168. (New) A membrane switch incorporating the silver-containing film made by the method of Claim 131.